

## Some Key Points

- Complex yet, robust construction well suited for the most complicated electronic products
- Solid rigid construction able to endure years of operation without failure
- Wide operating temperature range up to 255°C depending on the materials used
- Mount all component types – surface mount (SMT), thru – hole, wire bond and BGA
- Meets IPC-6012 Qualifications and Performance Specifications for Rigid Printed Boards

## Design Capabilities

- Layer Count: 3-20 conductive layers
- Material thickness: .031", .062", .093" and .125" typical
- Copper Thickness: ½ oz, 1 oz, 2 oz typical, 3oz, 4oz, 6oz non-typical
- Trace/Space: .003"/.003" typical, .002"/.002" non-typical
- Current Carrying Capacity: few milliamps to several amps
- Hole Size: .006" drilled not plated and .008" drilled plated typical